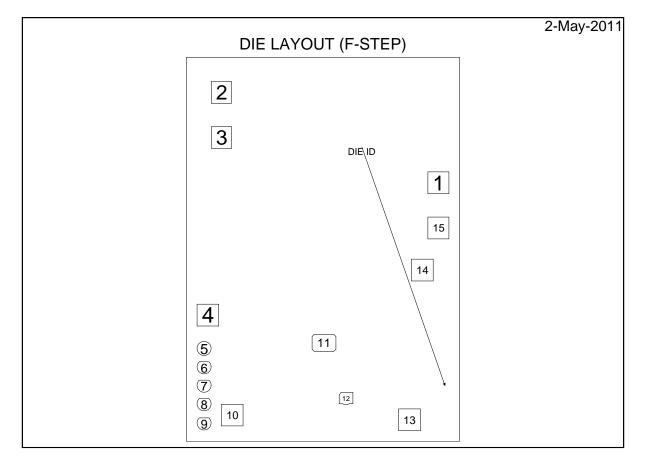


LM2940-5.0-MW8 1A LOW DROPOUT ADJUSTABLE REGULATOR



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information		
Physical Die	LM1940F	Bond Pad Opening	130.00µm x 140.00µm	
Identification		Size (min)		
Die Step	F	Bond Pad Metalization	AL 0.5%CU	
Physical	Attributes	Passivation	PECVDOX NITRIDE	
Wafer Diameter	152.4mm	Back Side Metal	Bare Back	
Die Size (Drawn)	1752.6µm x 2463.8µm	Back Side Connection	GND	
	69.0mils x 97.0mils			
Thickness	304.8µm Nominal			
Min Pitch	290.00µm			
Note: All values are round	ded to the nearest micron			
Special Assembly Requirements:				



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Die Bond Pad Coordinate Locations(F-Step) (Referenced to die center, coordinates in μ m) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
•		Х	Y	Х		Y
VIN	1	740.50	427.00	135.00	х	140.00
OUTPUT	2	-652.00	1007.00	130.00	х	140.00
OUTPUT	3	-652.00	717.00	130.00	х	140.00
OUTPUT	4	-738.50	-422.00	139.00	х	140.00
NC	5	-763.00	-636.00	90.00	х	89.95
NC	6	-762.97	-760.25	89.94	х	77.50
NC	7	-762.97	-878.25	89.94	х	77.50
NC	8	-762.97	-997.25	89.94	х	77.50
NC	9	-762.97	-1120.25	89.94	х	77.50
GND	10	-582.50	-1063.50	139.00	х	139.00
NC	11	6.50	-600.50	153.00	х	109.00
NC	12	148.00	-957.00	88.00	х	78.00
NC	13	555.00	-1094.00	140.00	х	140.00
GND	14	637.00	-133.00	140.00	х	140.00
VIN	15	740.50	137.00	135.00	х	140.00



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